

## 3D-P releases the e200 Intelligent Endpoint

Company expands mine networking product line with the e200 Intelligent Endpoint featuring a Rajant Instamesh® radio option.

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3D-P, a leading provider of technology products for the mining industry, is pleased to announce the addition of the e200 Intelligent Endpoint to the company's Intelligent Endpoint product portfolio.

The Intelligent Endpoint product line is a set of robust computing and communication devices designed specifically for mining and heavy industrial environments. The Intelligent Endpoints provide seamless integration and wireless networking for all on-machine mining applications including fleet management systems, machine health systems, high-precision GPS, slope monitoring, dewatering systems, video cameras, safety & security systems and more.

The e200 Intelligent Endpoint combines all the features of the existing e55, e56, e57 and e58 models in a single platform and adds new wireless connectivity options including Rajant InstaMesh®. Featuring a powerful dual-core processor, 2GB of memory and a 16GB of solid state drive, the e200 also boasts expanded application hosting capability.

The e200 provides all of the following key features:

- Intel® Bay Trail dual-core Atom @ 1.33GHz
- 2GB DDR3 Memory
- 16GB mSata SSD
- Linux OS
- 10 – 36VDC overload protected power
- Managed four port Gigabit Ethernet switch
- 6x RS-232 Serial ports
- 2x CAN ports
- 4x Digital IO
- 1x USB
- WAAS Capable GPS (GPS + GLONASS RTK Optional)
- Multiple radio options including:
  - Dual 802.11n Wifi
  - 802.11n plus LTE
  - Integrated Rajant ME4-2450R with InstaMesh® routing
- Same form factor and power cabling as the e5x Intelligent Endpoint models



“The e200 Intelligent Endpoint (IEP) gives us some new and exciting capability. The extra power allows the e200 to take full advantage of our application integration tools while hosting applications natively. The e200 is also the first IEP with a fully integrated Rajant InstaMesh® radio technology directly inside. These capabilities combine to help our customers reduce on-board technology clutter and the associated acquisition and maintenance costs.” stated Ron White, VP of Technology and CTO at 3D-P.

For more information, contact your 3D-P Account Manager, or visit [www.3d-p.com](http://www.3d-p.com). The e200 will also be showcased at the 2015 SME annual conference in Denver from February 15-18<sup>th</sup> at Booth #1952.